

NEO-FRD Series

DHF+Rinse+DRY

Key Features

- In-situ. DHF supply
- Le Chatelier's Principle
- Watermark Free
- Variety of option (Megasonic, DIO₃)
- Integration available
- Stable Etch Uniformity
(Minimized Design of Bath)



Specifications

ITEM	NEO-3000	REMARK
Particle@ ≤ 100nm	Hydrophobic: ≤ 50adders Hydrophilic : ≤ 30adders	Initial bare wafer Dryer only
Etching Uniformity	≤ 3 %	30 Å , 200:1 DHF Thermal Oxide Film
IPA Consumption	<90 cc /50wfs	
IPA/N ₂ Temperature	Room temp.	
IPA Generation	N ₂ bubbling	Hot(Optional)
HF Mixing	In-situ.	Room temp.
Watermark Haze	Free	
Total Process Time	RD:290~900" FRD:12~18'	DHF 200:1, 120 sec treatment/ IPA consumption ≤ 40 ml./run
Reliability	MTBF ≥ 1,000hrs MTTR ≥ 2hrs	Full function